

Layer Stack

Material	Layer	Thickness	Dielectric Material	Type	Df	Dk	Note	Description	Constructions
	Top Overlay			Legend					
Surface Material	Top Solder	0.015mm	Soldermask IPC-SM840	Solder Mask	0,028	3,5	used on rigid parts		
Nickel, Gold	Top Surface Finish	0.007mm		Surface Finish					
Outer Copper 1oz	Top Layer	0.035mm		Signal				Starting foil 1/2oz. after plating and processing	
Prepreg		0.220mm	WE-PP-0010	Dielectric	0,02	3,9	FR-4.0	Prepreg IPC-4101/21	2x2116
WE-ED-0004	Int1 (GND)	0.035mm		Signal				ED Base Copper	
Core		0.360mm	WE-CO-0008	Dielectric	0,02	4,1	FR-4.0	Core IPC-4101/21	2 x 7628
WE-ED-0004	Int2 (SIG)	0.035mm		Signal				ED Base Copper	
Prepreg		0.220mm	WE-PP-0010	Dielectric	0,02	3,9	FR-4.0	Prepreg IPC-4101/21	2x2116
WE-ED-0004	Int3 (PWR)	0.035mm		Signal				ED Base Copper	
Core		0.360mm	WE-CO-0008	Dielectric	0,02	4,1	FR-4.0	Core IPC-4101/21	2 x 7628
WE-ED-0004	Int4 (GND)	0.035mm		Signal				ED Base Copper	
Prepreg		0.220mm	WE-PP-0010	Dielectric	0,02	3,9	FR-4.0	Prepreg IPC-4101/21	2x2116
Outer Copper 1oz	Bottom Layer	0.035mm		Signal				Starting foil 1/2oz. after plating and processing	
Nickel, Gold	Bottom Surface Finish	0.007mm		Surface Finish					
Surface Material	Bottom Solder	0.015mm	Soldermask IPC-SM840	Solder Mask	0,028	3,5	used on rigid parts		
	Bottom Overlay			Legend					

Total thickness: 1.634mm

NOTES: UNLESS OTHERWISE SPECIFIED.

1. FABRICATE PER IPC-6012A CLASS 2.
2. FOR BOARD THICKNESS AND IMPEDANCE DETAILS REFER STACKUP DOCUMENT.
3. SURFACE FINISH: IMMERSION GOLD (ENIG)
4. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE LPI, COLOR GREEN.
5. SILK SCREEN LEGEND TO BE APPLIED PER LAYER STACKUP USING WHITE NON-CONDUCTIVE EPOXY INK.
6. THIS PRINTED CIRCUIT BOARD IS DESIGNED WITH A MINIMUM CONDUCTOR WIDTH AND SPACING OF 0.127MM & 0.127MM.
7. ALL VIAS ARE TENTED ON BOTH SIDES UNLESS SOLDERMASK OPENED IN GERBER.
8. ALL VIAS ON PAD SHOULD BE FILLED WITH NON CONDUCTIVE EPOXY.
9. SOLDER MASK OPENING IS KEPT SAME SIZE AS PAD (1:1) FOR ALL COMPONENTS
10. MANUFACTURER'S IDENTIFICATION, DATECODE LETTER SHALL BE SILKSCREENED ON SOLDER SIDE OF THE BOARD.
11. TRACE WIDTH SHOULD BE ACCURATELY ETCHED. MAX TOLERANCE +/- 1 MIL
12. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
13. PCB MATERIAL REQUIREMENTS:
- A. Tg 135 C OR EQUIVALENT.
14. LAYER TO LAYER REGISTRATION SHALL BE WITHIN +/-2 MIL

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Date	04.04.2024		
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Total pages	1	BLE sensor	Rev.1
Page size	A4		
Materials			